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United States Patent [19]

Boucher et al.

[11] **Patent Number:** **Des. 381,668**

[45] **Date of Patent:** ****Jul. 29, 1997**

[54] **SEMICONDUCTOR WAFER DICING SAW**

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[**] Term: **14 Years**

[21] Appl. No.: **56,175**

[22] Filed: **Jun. 25, 1996**

[51] **LOC (6) Cl.** **15-09**

[52] **U.S. Cl.** **D15/133**; D15/127

[58] **Field of Search** D15/127, 133; 88/404; 125/13.01, 35; 437/226, 227; 451/21, 6

[56] **References Cited**

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[57] **CLAIM**

The ornamental design for a semiconductor wafer dicing saw, as shown and described.

DESCRIPTION

FIG. **1** is a top, left front perspective view of a semiconductor wafer dicing saw showing our new design;
FIG. **2** is a right side elevational view thereof, the left side view being a mirror image;
FIG. **3** is a top plan view thereof;
FIG. **4** is a bottom plan view thereof;
FIG. **5** is a rear elevational view thereof;
FIG. **6** is a top, left perspective view of a second embodiment of FIG. **1**, the difference being inclusion of a camera, blade housing and chuck;
FIG. **7** is a top plan view of FIG. **6**;
FIG. **8** is a right side elevational view of FIG. **6**;
FIG. **9** is a left side elevational view of FIG. **6**;
FIG. **10** is a bottom plan view of FIG. **6**; and,
FIG. **11** is a rear elevational view of FIG. **6**.
The broken line showing of camera, blade housing and chuck in FIGS. **1–3** and **5** is for illustrative purposes only and forms no part on the claimed design for the embodiment of FIGS. **1–5**.

1 Claim, 2 Drawing Sheets

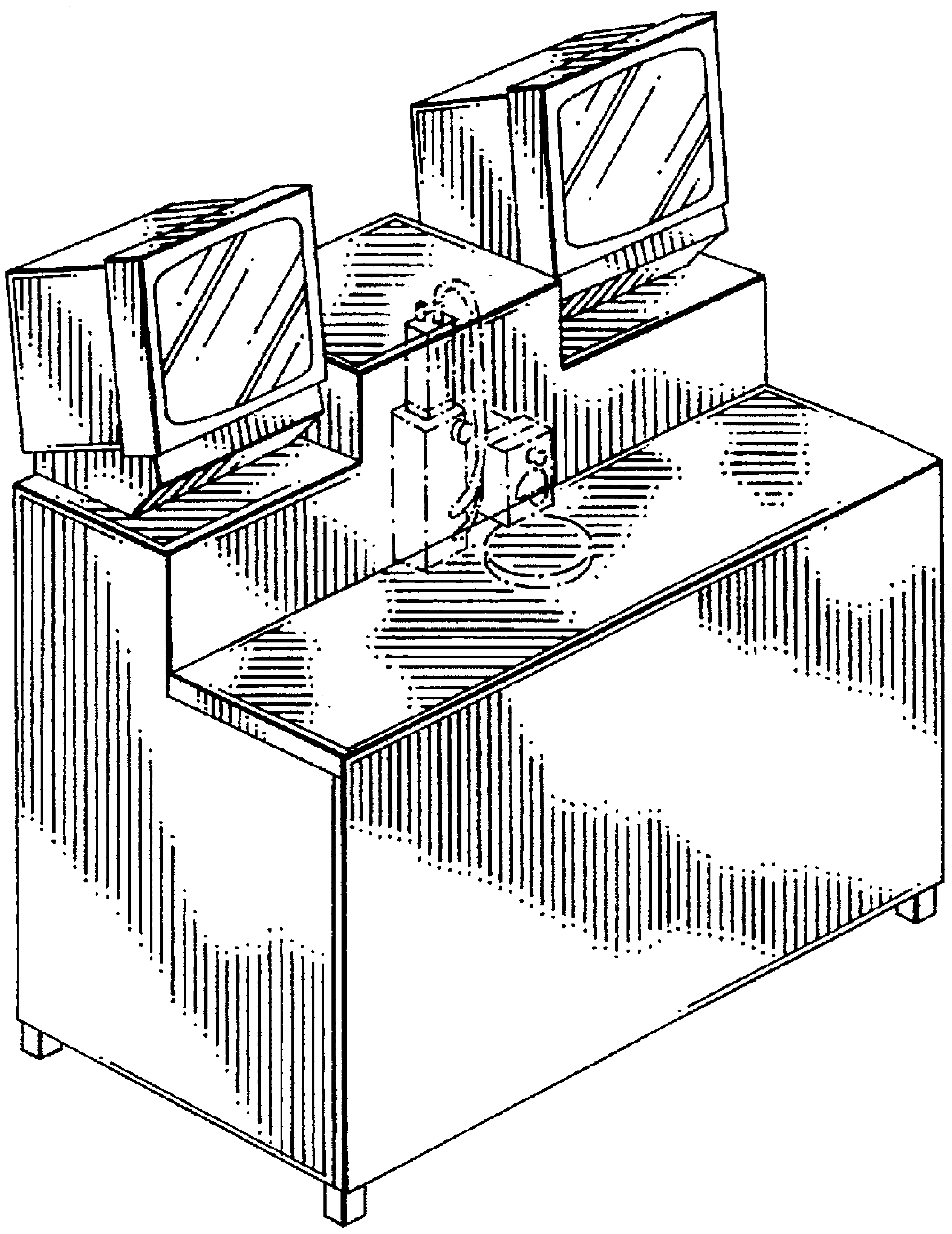
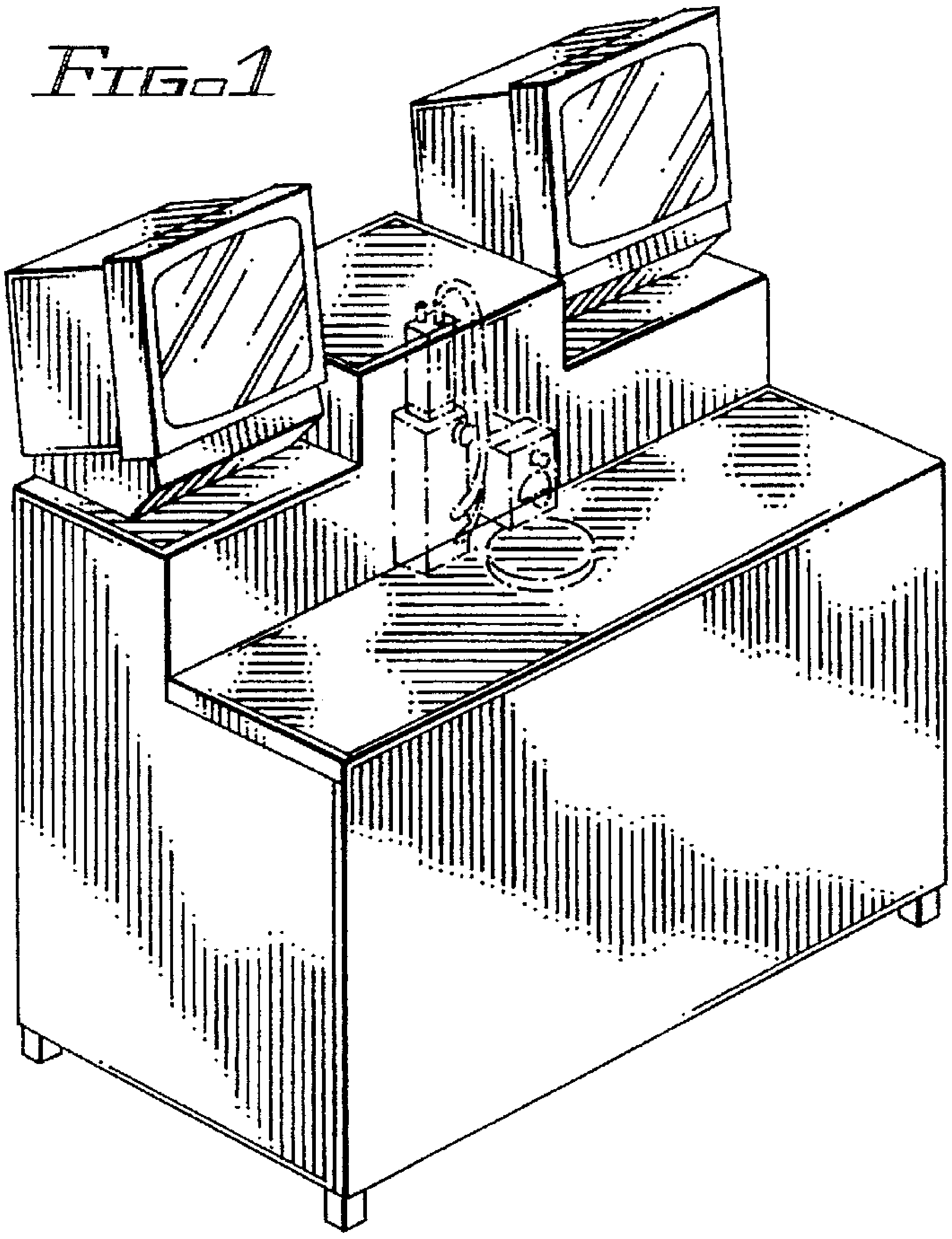


FIG. 1



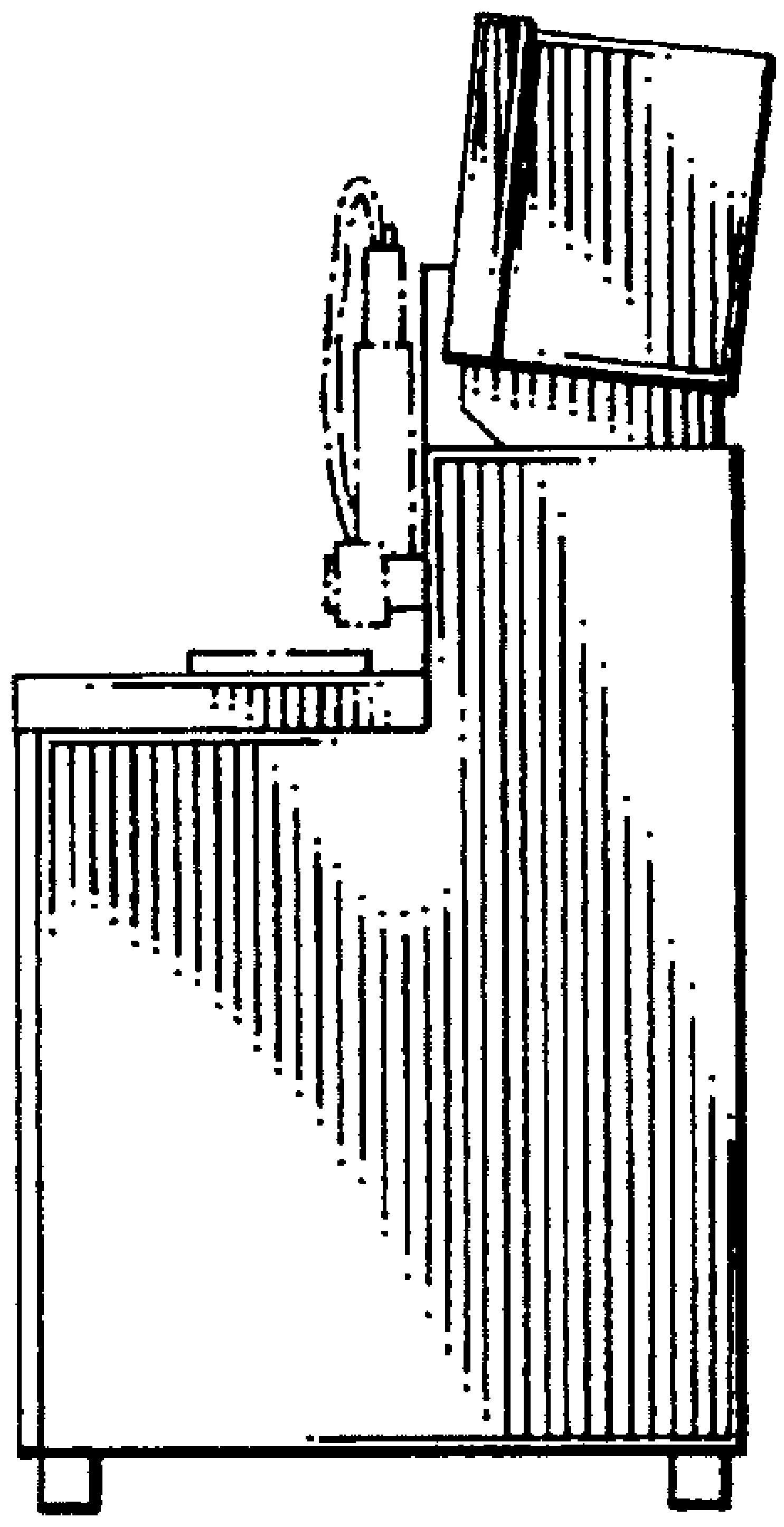


FIG. 2

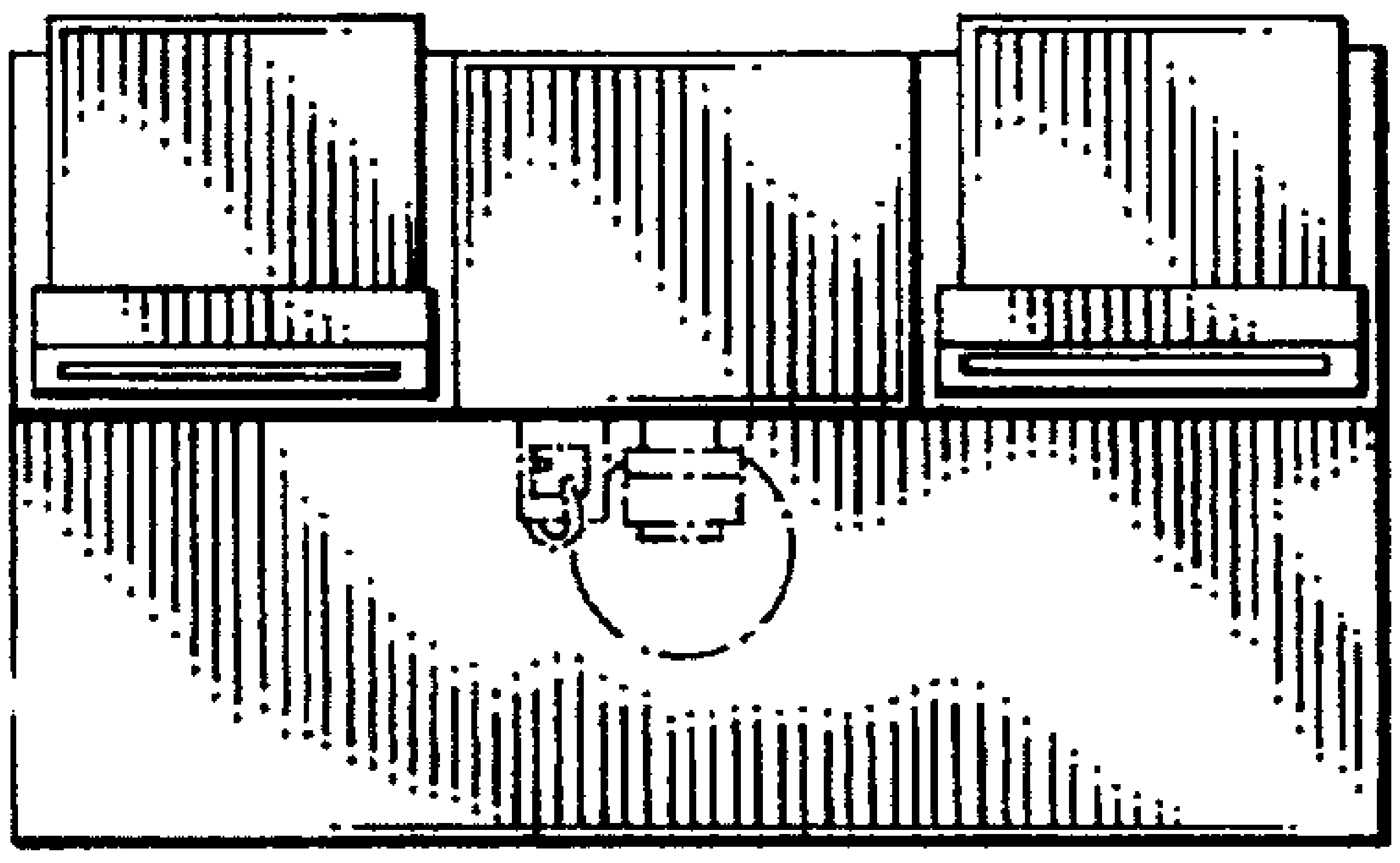


FIG. 3

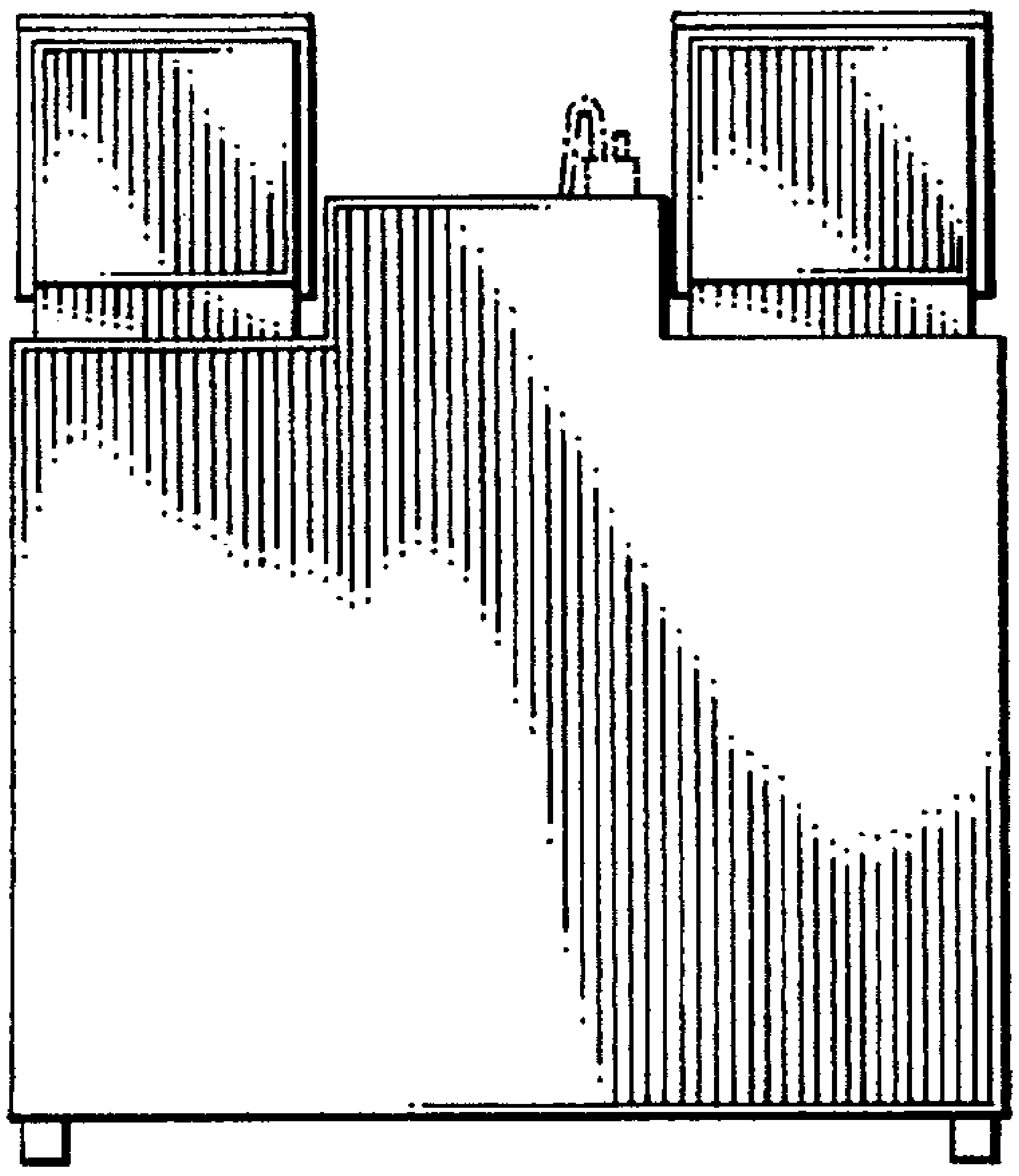


FIG. 5

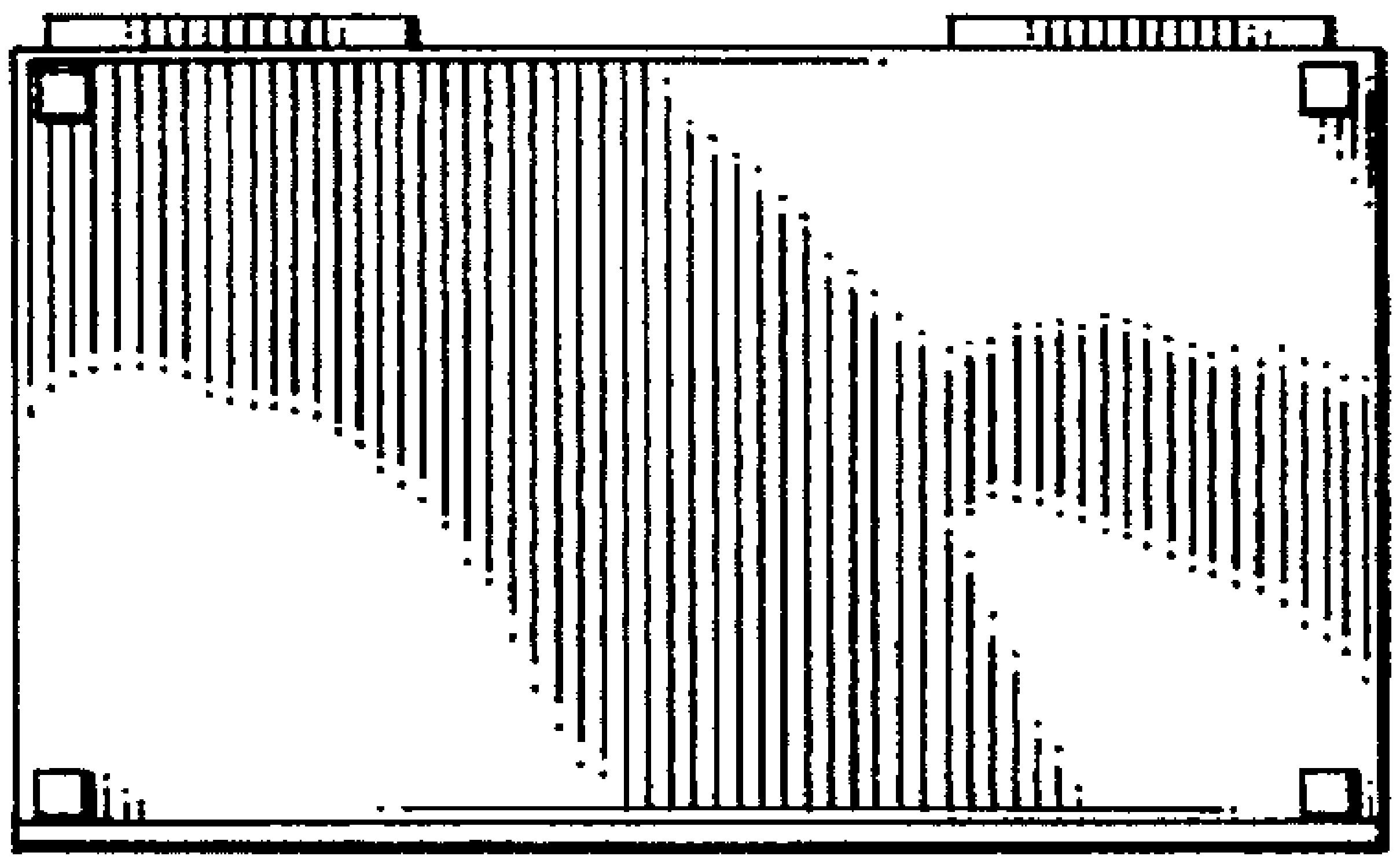


FIG. 4

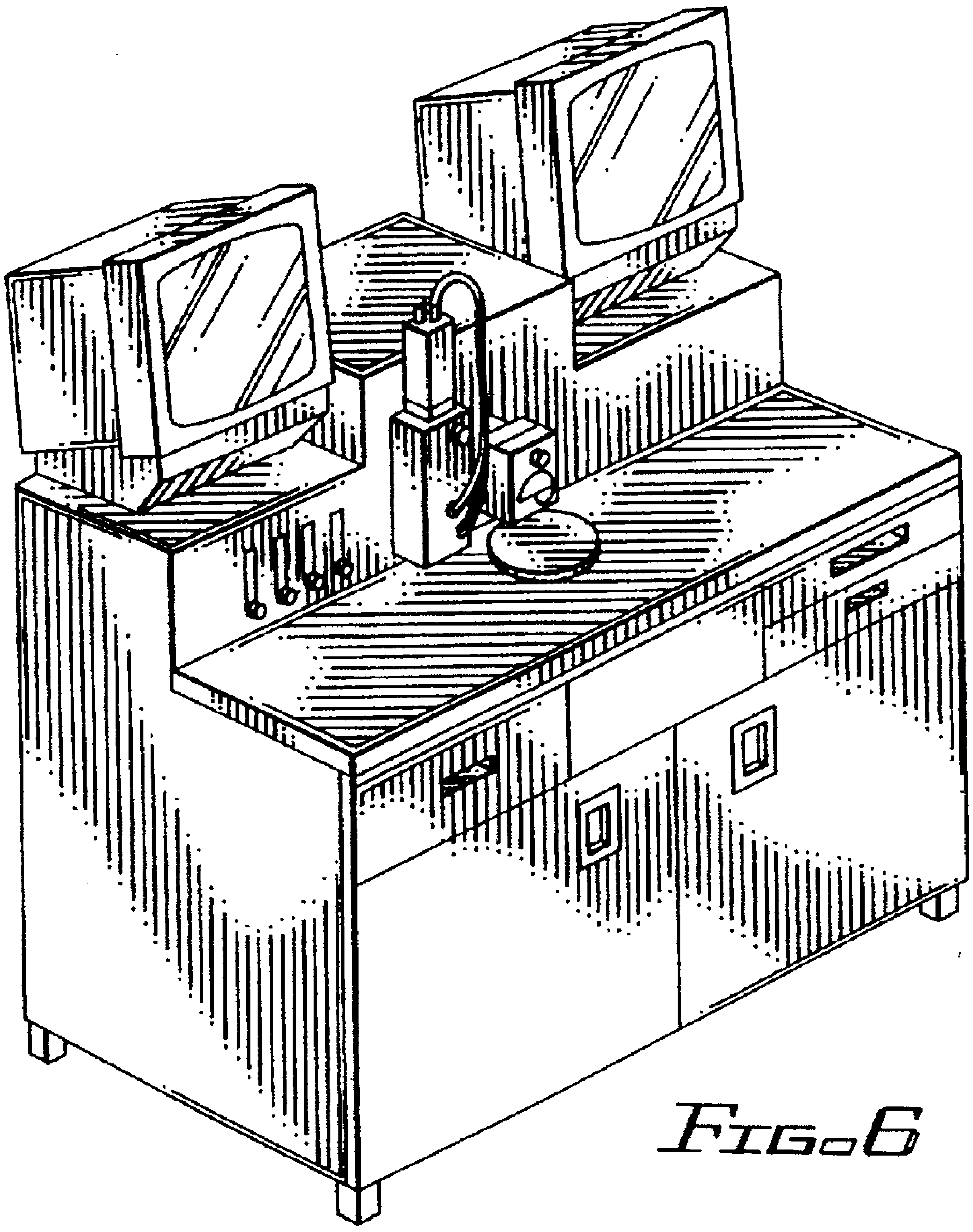


FIG. 6

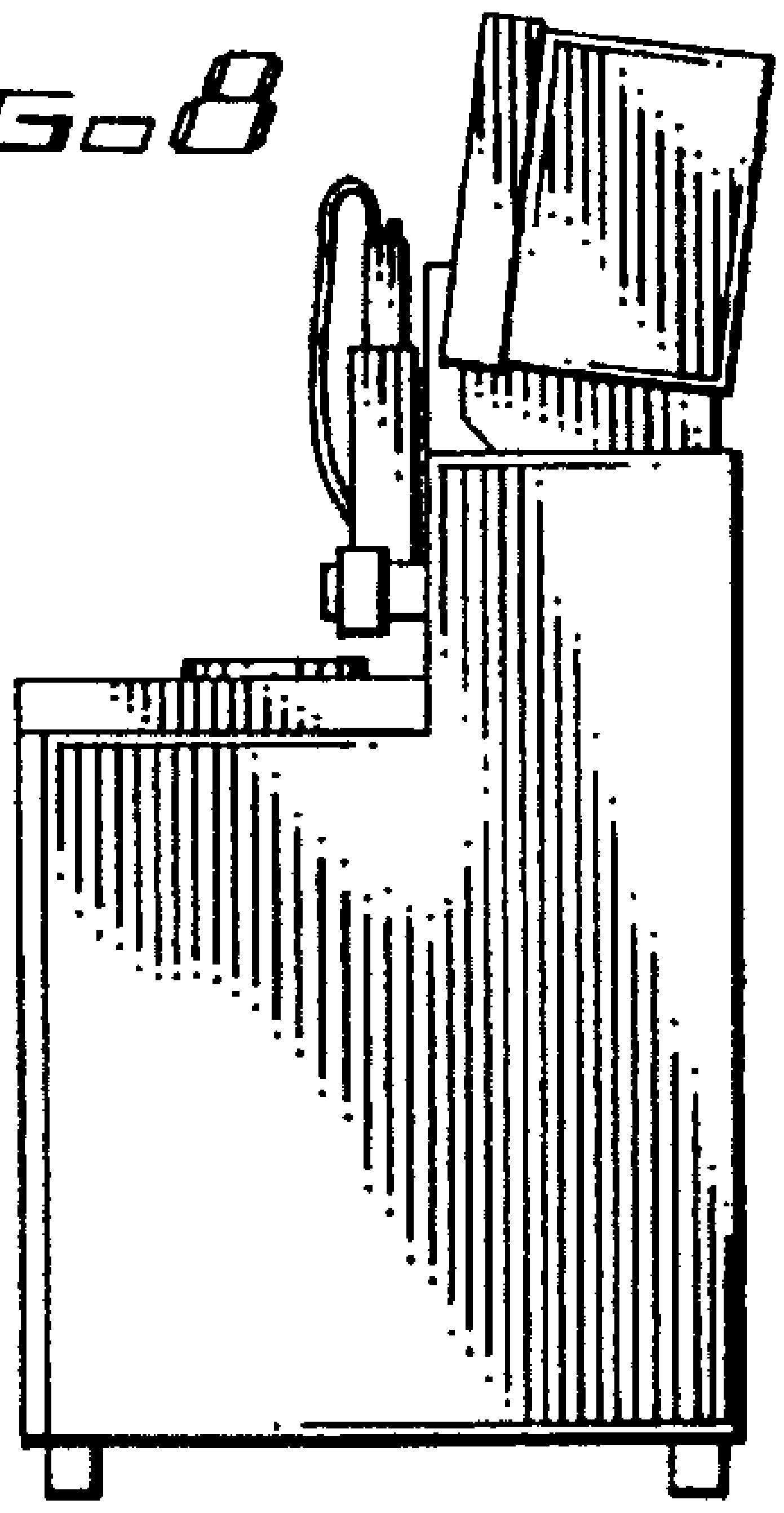


FIG. 8

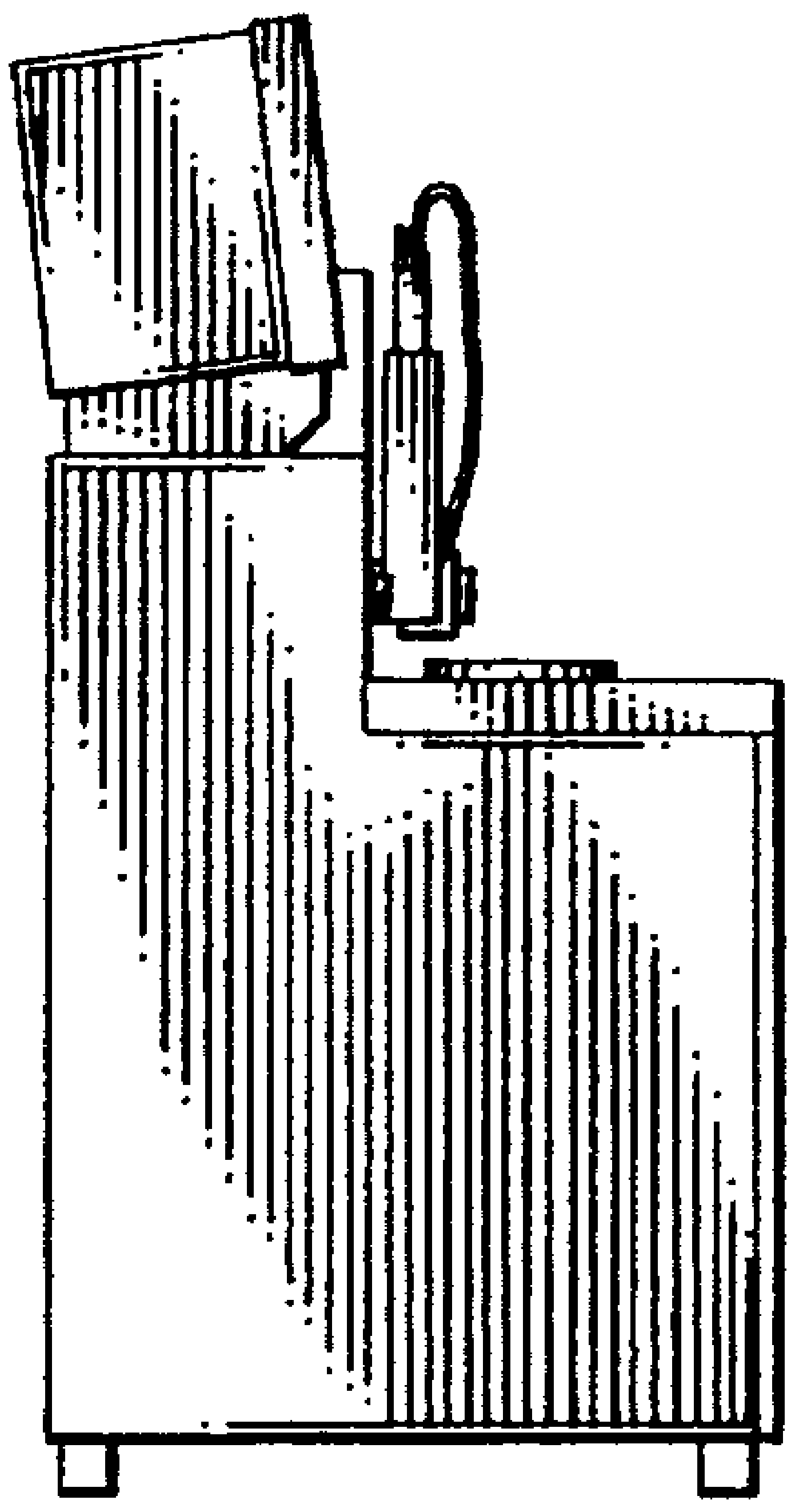


FIG. 9

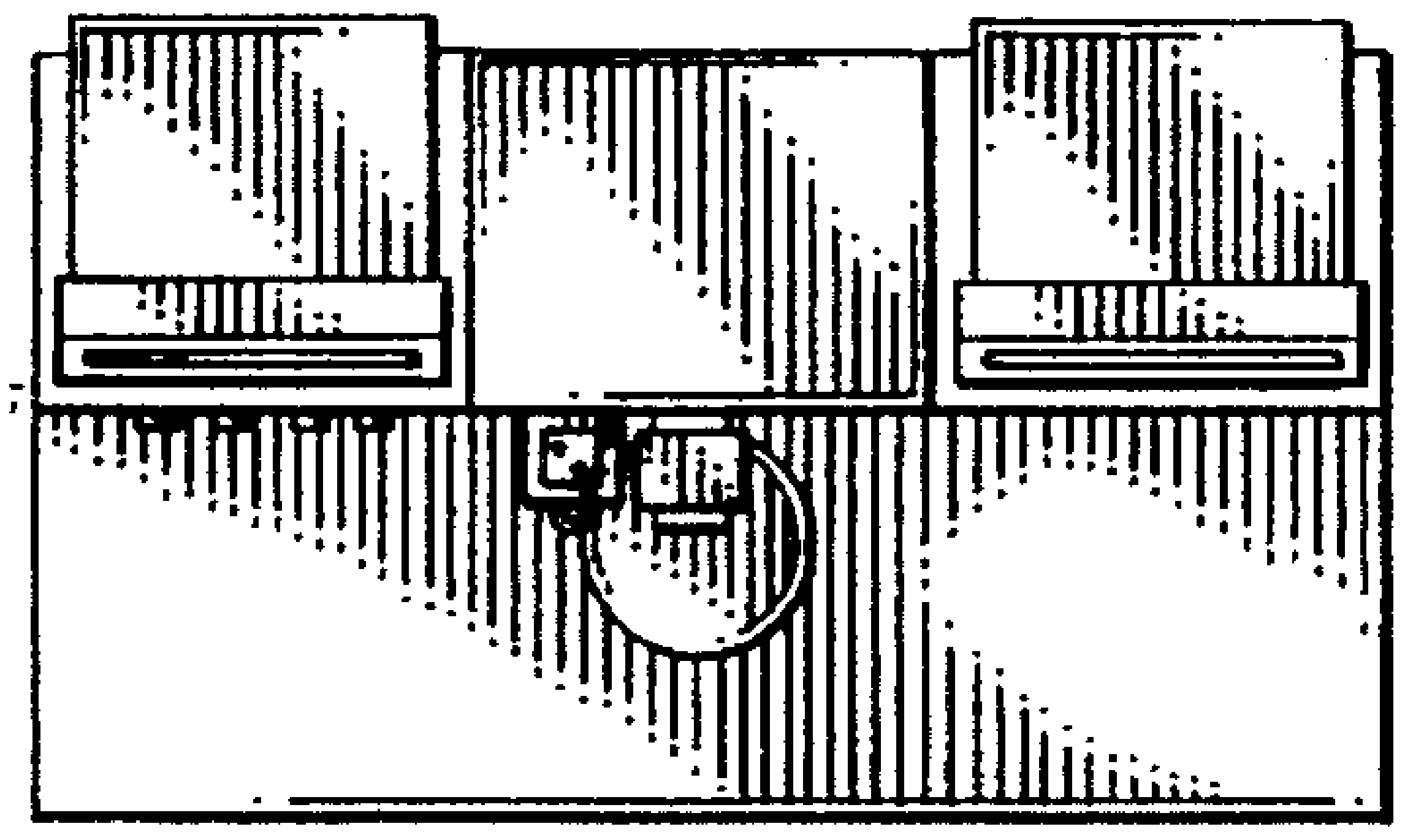


FIG. 7

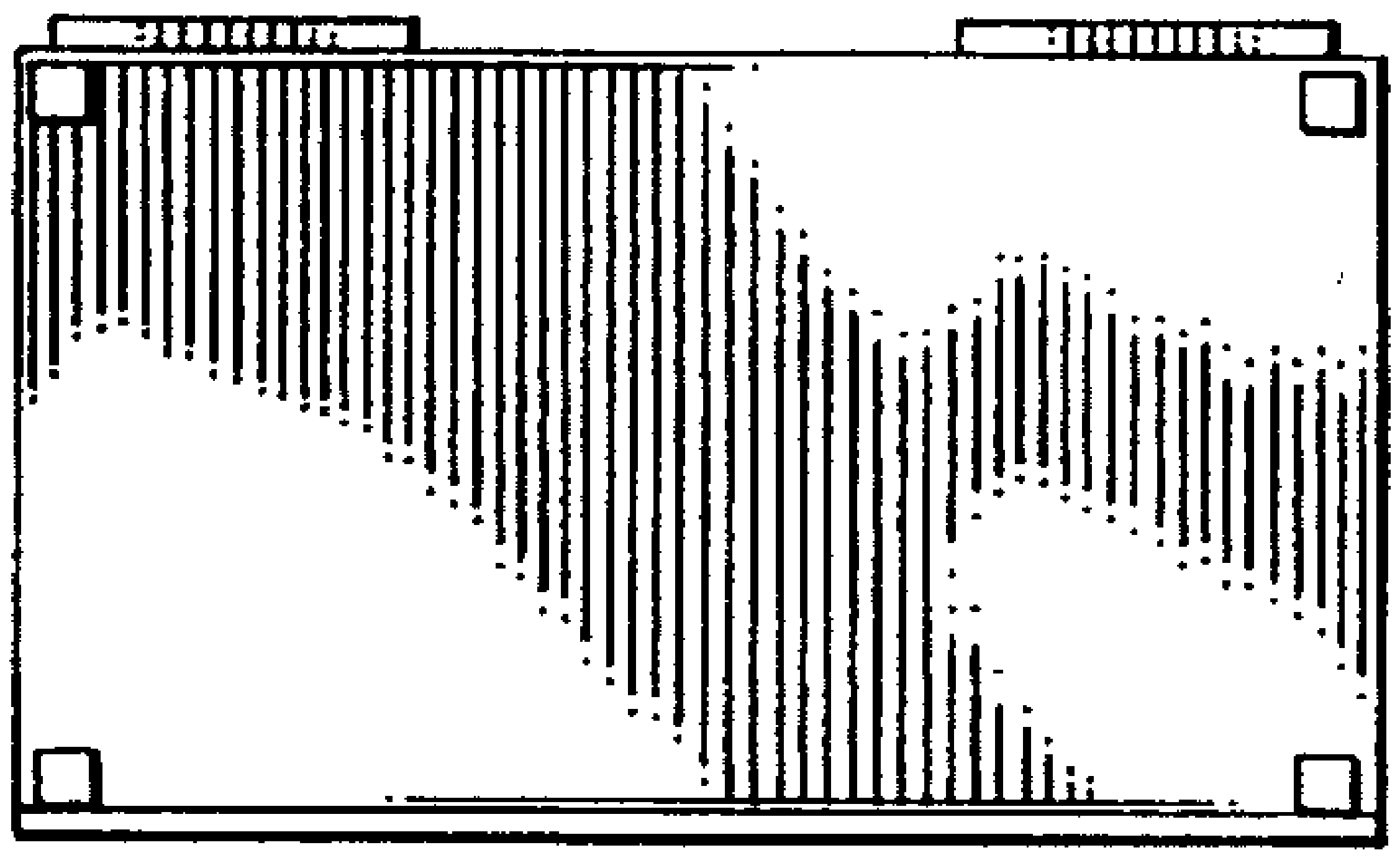


FIG. 10

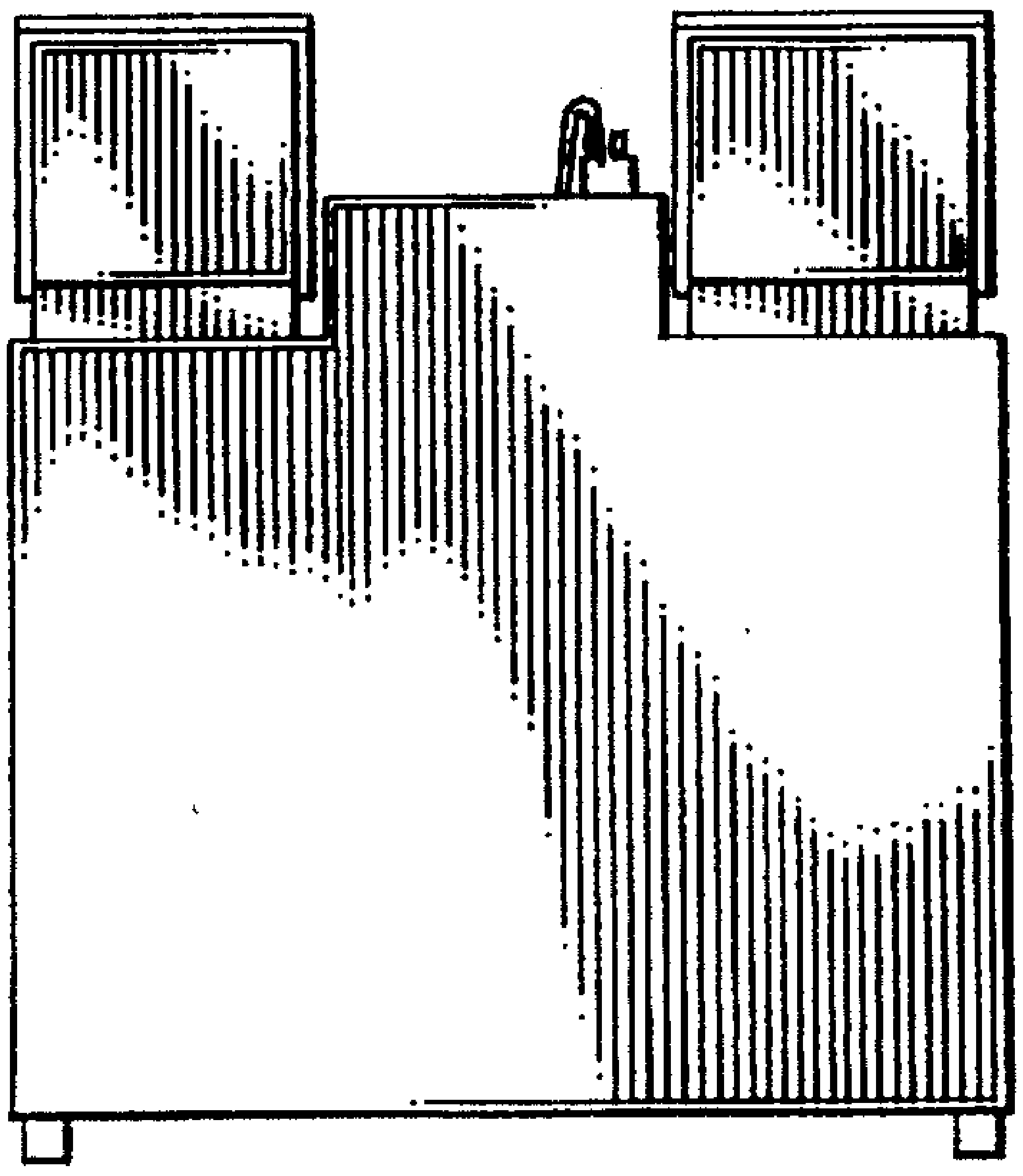


FIG. 11